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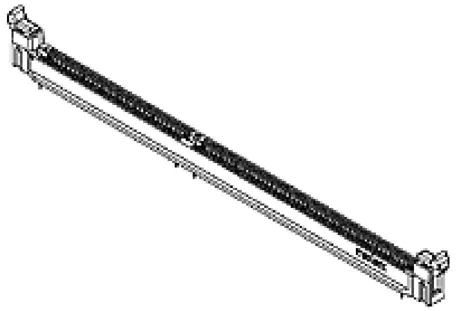
Part Number:	**0783150001**
Status:	**Active**
Description:	1.00mm (.039") Pitch DDR3 DIMM Socket, Very Low Profile, Vertical, Press-Fit, with Pegs, Black Housing and Latches, 0.76µm (30µ") Gold (Au)Plating, 1.85mm (.073") Compliant Pin Length, 2.40mm (.094") PCB Thickness, 240 Circuits, Lead free

Documents:

3D Model	Product Specification PS-78315-001 (PDF)
Drawing (PDF)	RoHS Certificate of Compliance (PDF)



Series image - Reference only

Agency Certification

CSA	LR19980
UL	E29179

General

Product Family	Memory Module Sockets
Series	78315
Component Type	Socket
JEDEC Outline	MO-269
Product Name	DDR3 DIMM

Physical

Circuits (Loaded)	240
Circuits (maximum)	240
Color - Resin	Black
Durability (mating cycles max)	25
Entry Angle	Vertical
Flammability	94V-0
Function Key	None
Keying to Mating Part	Yes
Material - Metal	Copper Alloy
Material - Plating Mating	Gold
Material - Plating Termination	Tin
Material - Resin	Nylon
PC Tail Length (in)	0.073 In
PC Tail Length (mm)	1.85 mm
PCB Locator	Yes
PCB Retention	Yes
PCB Thickness Recommended (in)	0.095 In
PCB Thickness Recommended (mm)	2.40 mm
Packaging Type	Tray
Pitch - Mating Interface (in)	0.039 In
Pitch - Mating Interface (mm)	1.00 mm
Pitch - Term. Interface (in)	0.039 In
Pitch - Term. Interface (mm)	1.00 mm
Plating min: Mating (µin)	30
Plating min: Mating (µm)	0.76
Plating min: Termination (µin)	15
Plating min: Termination (µm)	0.38
Temperature Range - Operating	-55°C to +85°C
Termination Interface: Style	Through Hole - Compliant Pin

Electrical

Current - Maximum per Contact	1A
Voltage - Maximum	30V AC (RMS)/DC
Voltage Key	Center

EU RoHS

China RoHS

ELV and RoHS Compliant

REACH SVHC

Contains SVHC: No

Halogen-Free Status

Not Halogen-Free

Need more information on product environmental compliance?

Email productcompliance@molex.com
For a multiple part number RoHS Certificate of Compliance, click here

Please visit the Contact Us section for any non-product compliance questions.

Search Parts in this Series
78315Series

Mates With
JEDEC standard 1.27mm modules

Material Info

Reference - Drawing Numbers

Product Specification	PS-78315-001, RPS-78315-001
Sales Drawing	SD-78315-001

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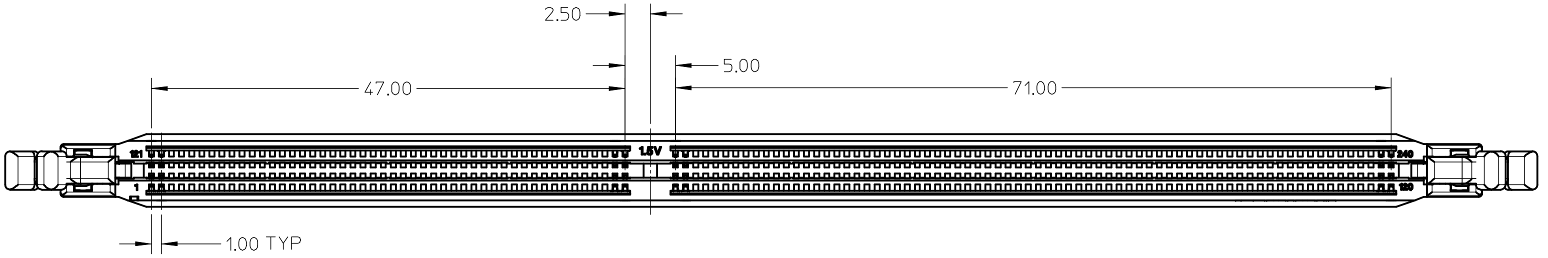
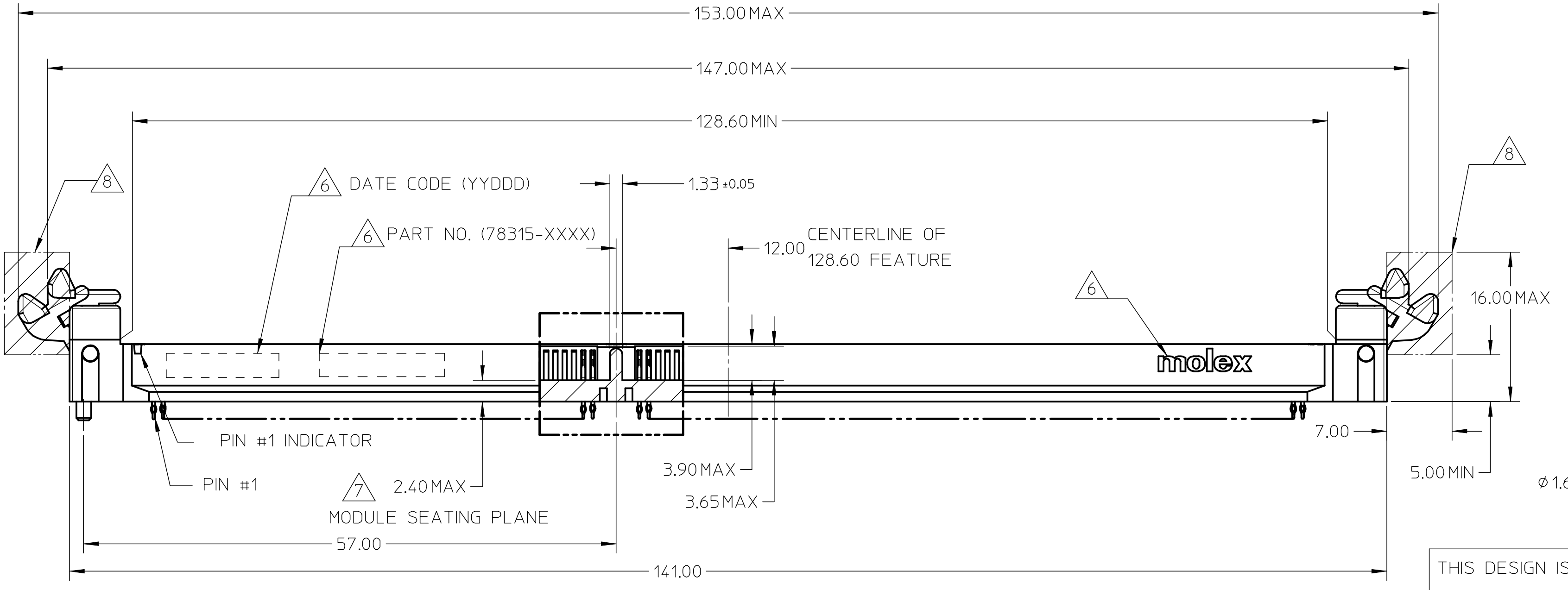
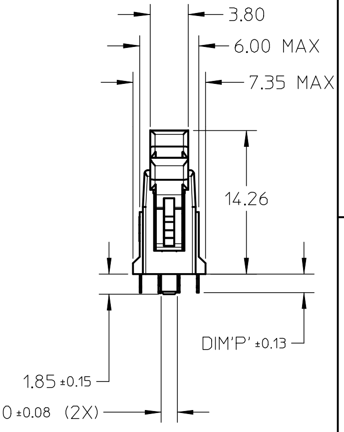






THIS DESIGN IS BASED ON DESIGN OBJECTIVES AND IS STRICTLY TENTATIVE. IT MAY CHANGE BASED ON RESULTS OF ADDITIONAL DESIGN REVIEWS & VERIFICATIONS.

NOTES:

1. MATERIAL:
   HOUSING - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
   LATCH - POLYAMIDE (PA) GLASS FILLED, UL 94V-0, COLOR - BLACK
   TERMINAL - COPPER ALLOY
2. FINISHES: TERMINAL PLATING SEE TABLE ON SHEET 5
3. PRODUCT SPECIFICATION: PS-78315-001
4. PACKAGING SPECIFICATION: PRODUCT SHALL BE PACKED IN TRAYS
5. CARD SLOT ACCEPTS 1.27 +/- 0.10MM MODULE THICKNESS (MEASURED FROM PC PADS)
6. MOLEX LOGO, DATE & PART NUMBERS INDICATED ON HOUSING
7. MODULE SEATING PLANE FROM TOP OF PCB
8. KEEP OUT ZONE RESERVED FOR LATCH

REV	DESCRIPTION
3	ADDED OPTION EC NO: S2009-0332 DRWN:CCTEH 2009/05/25 CH'KD:CGTAN 2009/05/25 APPR:SHLENI 2009/05/27

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

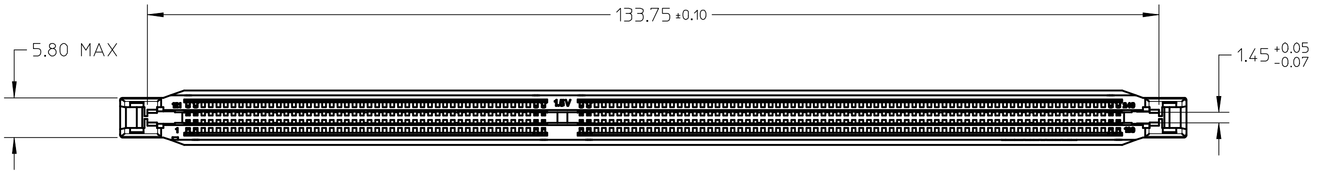
		DATE
DRAWN BY	CMTEO	2008/07/17
CHECKED BY	CCTEH	2008/07/30
APPROVED BY	SHLENI	2008/08/01

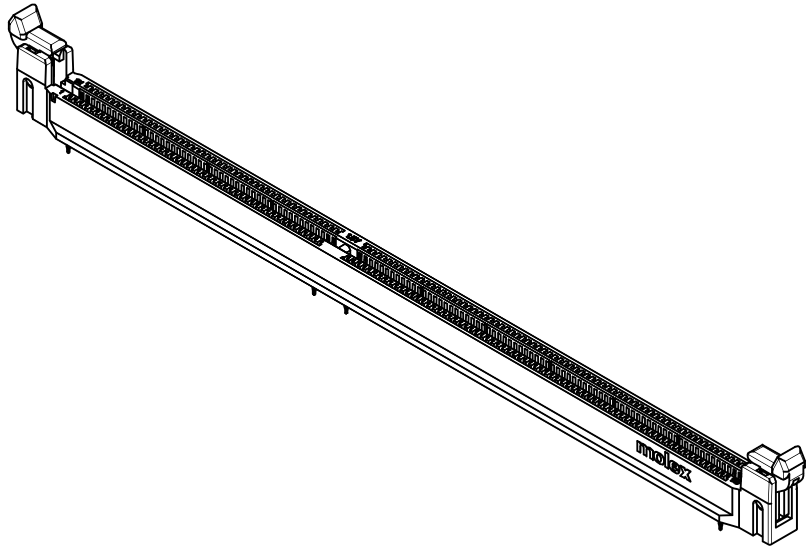
TITLE
DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

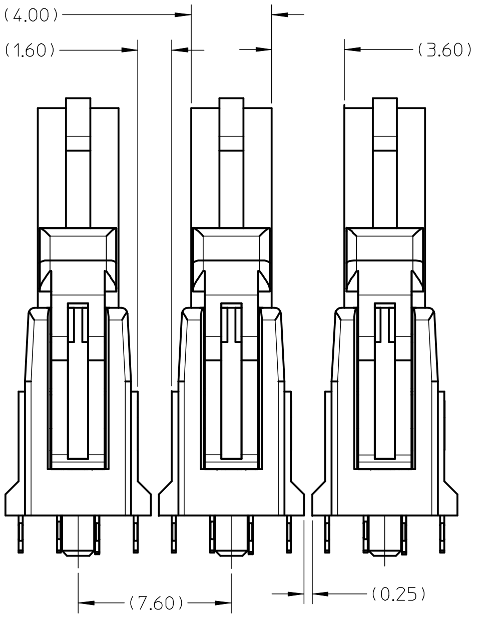
MOLEX INCORPORATED

MATERIAL NO.: SEE TABLE
DOCUMENT NO.: SD-78315-001
SHEET NO.: 1 OF 6
SIZE: A3

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION







MINIMUM ROW TO ROW SPACING RECOMMENDATION
(USING 4.00MM MODULE CARD)

REV	DESCRIPTION
3	ADDED OPTION EC NO: S2009-0332 DRWN:CCTEH 2009/05/25 CH'KD:CGTAN 2009/05/25 APPR:SHLENI 2009/05/27

QUALITY SYMBOLS
▼=0
▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

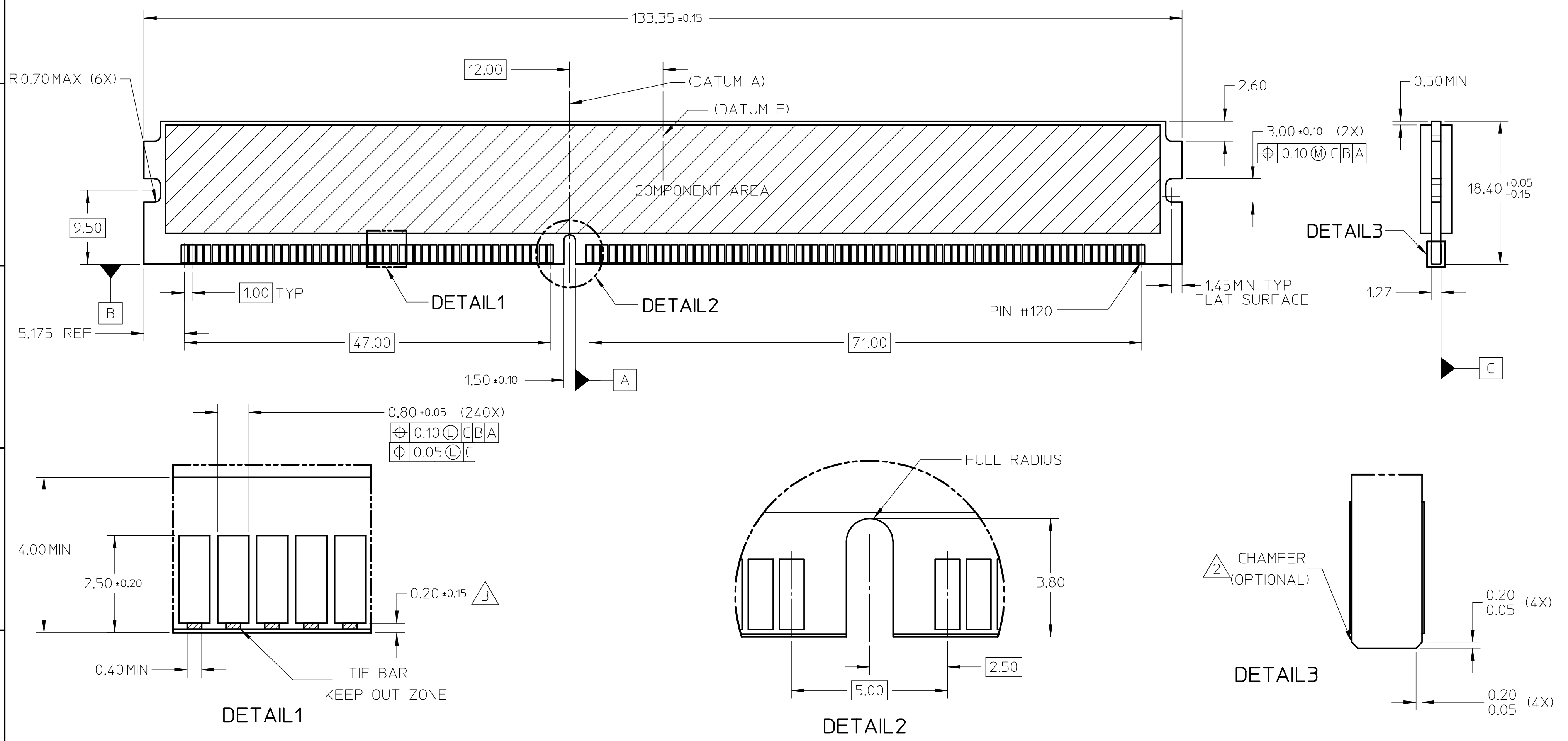
	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE MM ONLY	SCALE NTS	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
DRAWN BY CMTEO	DATE 2008/07/17	TITLE DDR3 DIMM (LSP, VLP) 1.00MM PITCH, 240 CKTS VERTICAL P/F, LOWLLCR		
CHECKED BY CCTEH	DATE 2008/07/30			
APPROVED BY SHLENI	DATE 2008/08/01	molex MOLEX INCORPORATED		
MATERIAL NO. SEE TABLE		DOCUMENT NO. SD-78315-001		SHEET NO. 2 OF 6
SIZE A3				

THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION

009MODULE CARD
DDR3 DUAL INLINE MEMORY MODULE FAMILY 1.00 CONTACT CENTERS
(JEDEC MO-269, ISSUE A, 12/05)



NOTES:

1. RECOMMENDED PLATING FOR CONTACT PADS:
   PREFERRED: 0.76 MICROMETERS GOLD PLATING MIN
   OVER 2.00 MICROMETERS NICKEL
   ALTERNATIVE: 0.05-0.75 MICROMETERS GOLD PLATING
   OVER 2.00 MICROMETERS NICKEL MUST
   USE AN ELECTRONIC CONTACT GRADE
   CORROSIVE BARRIER LUBRICANT
2. CHAMFER IS OPTIONAL AND IS NOT TO HIT THE GOLD PADS
3. LEADING EDGE OF GOLD PADS SPECIFIED BY KEEPOUT ZONE
   SHALL BE FREE OF BURRS AND EXTERNAL TIE BARS

3 ADDED OPTION
EC NO: S2009-0332
DRWN:CCTEH 2009/05/25
CH'KD:CGTAN 2009/05/25
APPR:SHLENI 2009/05/27
REV DESCRIPTION

QUALITY SYMBOLS
▼=0
Ⓒ=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

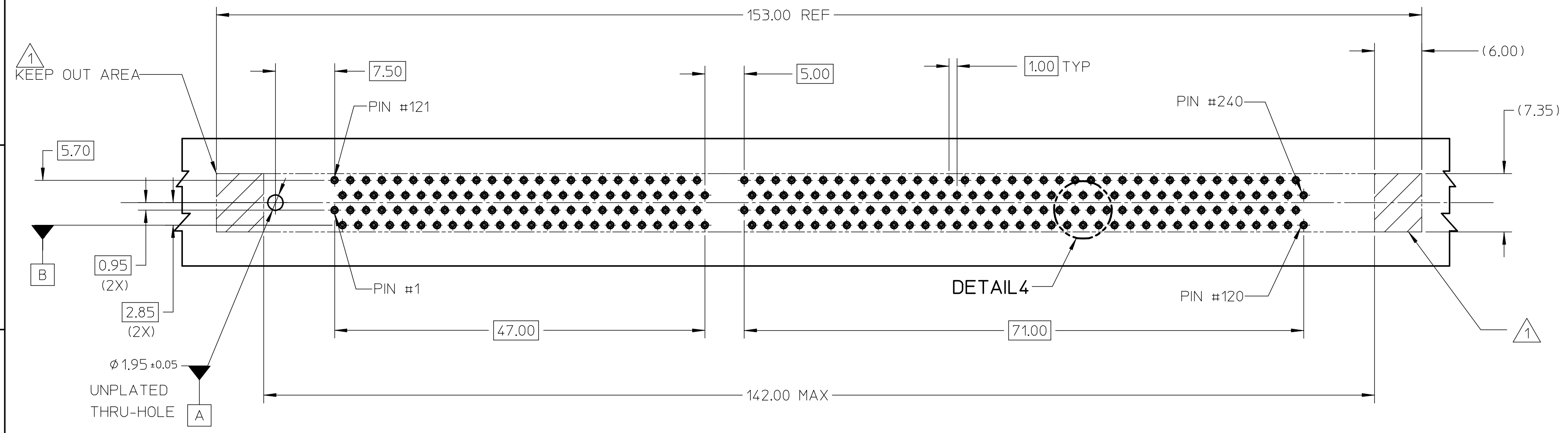
DIMENSION STYLE: MM ONLY
SCALE: NTS
DESIGN UNITS: METRIC
THIRD ANGLE PROJECTION

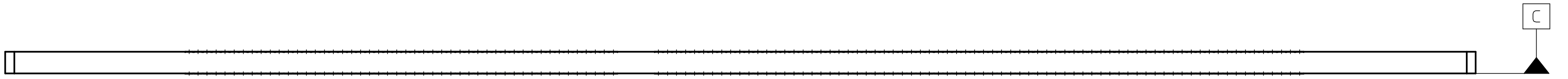
DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2008/08/01

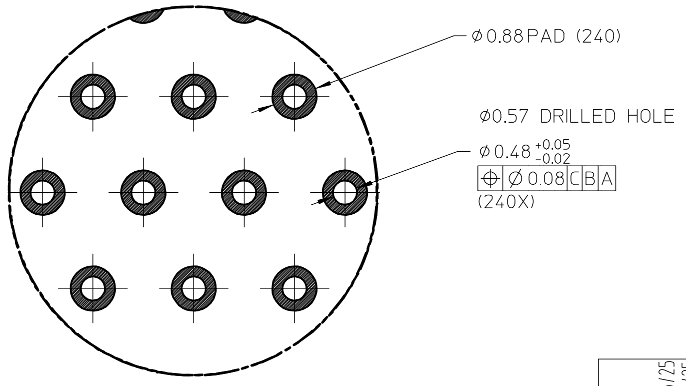
TITLE
DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

molex MOLEX INCORPORATED

MATERIAL NO. SEE TABLE
DOCUMENT NO. SD-78315-001
SHEET NO. 3 OF 6
SIZE A3







DETAIL4

NOTES:

1. KEEPOUT AREA IS THE AREA WHERE THE CONNECTOR (INCLUDING LATCH) IS MOUNTED ON THE PCB

REV	3
DESCRIPTION	ADDED OPTION EC NO: S2009-0332 DRWN:CCTEH 2009/05/25 CH'KD:CGTAN 2009/05/25 APPR:SHLENI 2009/05/27

QUALITY SYMBOLS

▼=0

▽=0

GENERAL TOLERANCES (UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS

DIMENSION STYLE	SCALE	DESIGN UNITS	
MM ONLY	NTS	METRIC	THIRD ANGLE PROJECTION

DRAWN BY	CMTEO	DATE 2008/07/17
CHECKED BY	CCTEH	DATE 2008/07/30
APPROVED BY	SHLENI	DATE 2008/08/01
MATERIAL NO.	SEE TABLE	
SIZE	A3	

TITLE

DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

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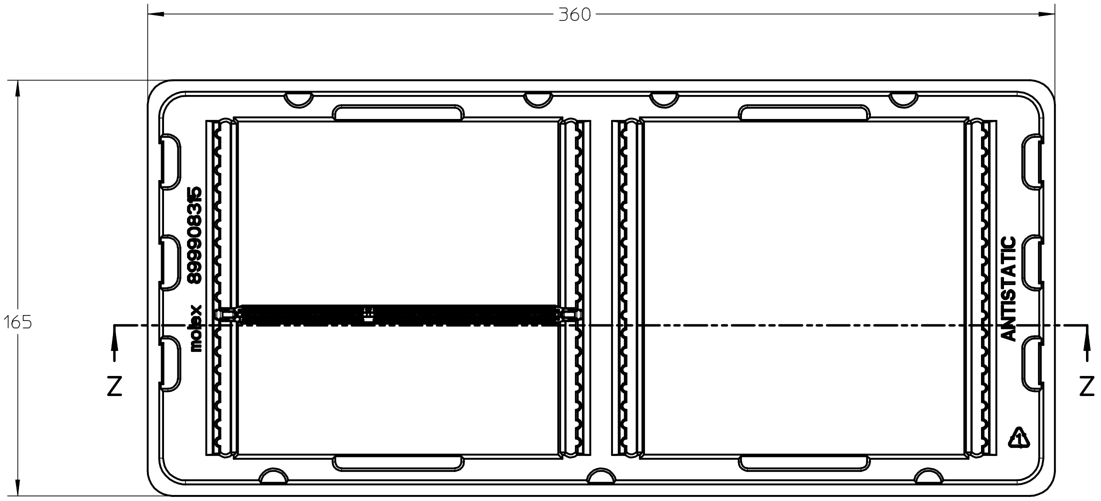
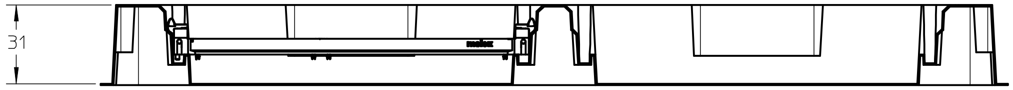
DOCUMENT NO. SD-78315-001

SHEET NO. 4 OF 6

VIEW FOR PACKAGING TRAY





SECTION Z-Z

NOTE:

1. NO. OF CAVITY - 18 X 2 =36

3	ADDED OPTION EC NO: S2009-0332 DRWN:CCTEH 2009/05/25 CH'KD:CGTAN 2009/05/25 APPR:SHLENI 2009/05/27	
REV	DESCRIPTION	

QUALITY SYMBOLS
▼=0
∇ C =0

GENERAL TOLERANCES (UNLESS SPECIFIED)	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---
ANGULAR ± 1 °		

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE: MM ONLY	SCALE: NTS	DESIGN UNITS: METRIC
DRAWN BY: CMTEO	DATE: 2008/07/17	
CHECKED BY: CCTEH	DATE: 2008/07/30	
APPROVED BY: SHLENI	DATE: 2008/08/01	
MATERIAL NO.: SEE TABLE	DOCUMENT NO.: SD-78315-001	SHEET NO.: 5 OF 6
SIZE: A3		

THIRD ANGLE PROJECTION

TITLE
DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

MOLEX INCORPORATED

PART NO.	KEY POS.	DIM 'P'	RECOMMENDED PCB THICKNESS	PLATING OPTION	
				CONTACT AREA	TAIL AREA
78315-0001	CENTER (1.5V)	1.85	2.40	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0201				0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN/LEAD (BRIGHT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE
78315-0011		2.85	2.60	0.76 MICROMETER/ 30 MICROINCH MIN. GOLD OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE	0.38 TO 1.52 MICROMETER/15 TO 60 MICROINCH MIN TIN (MATT) OVER 1.27 MICROMETER/ 50 MICROINCH MIN. NICKEL UNDERPLATE

REV	DESCRIPTION
3	ADDED OPTION EC NO: S2009-0332 DRWN:CCTEH 2009/05/25 CH'KD:CGTAN 2009/05/25 APPR:SHLENI 2009/05/27

QUALITY SYMBOLS
▼=0
▽C=0

GENERAL TOLERANCES
(UNLESS SPECIFIED)

	mm	INCH
4 PLACES	± ---	± ---
3 PLACES	± ---	± ---
2 PLACES	± 0.20	± ---
1 PLACE	± ---	± ---

ANGULAR ± 1 °

DRAFT WHERE APPLICABLE
MUST REMAIN
WITHIN DIMENSIONS

DIMENSION STYLE
MM ONLY

SCALE
NTS

DESIGN UNITS
METRIC

THIRD ANGLE
PROJECTION

DRAWN BY	DATE
CMTEO	2008/07/17
CHECKED BY	DATE
CCTEH	2008/07/30
APPROVED BY	DATE
SHLENI	2008/08/01

TITLE
DDR3 DIMM (LSP, VLP)
1.00MM PITCH, 240 CKTS
VERTICAL P/F, LOWLLCR

molex MOLEX INCORPORATED

MATERIAL NO.
SEE TABLE

DOCUMENT NO.
SD-78315-001

SHEET NO.
6 OF 6

SIZE
A3